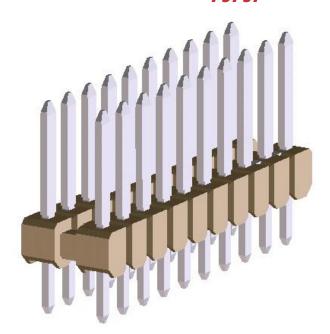
FEATURES AND SPECIFICATIONS

molex

3.50mm (.138") Pitch MX150™ Dual-Row Unshrouded Breakaway Header

75757



Flexible design permits customers to standardize PCB layouts and reduce inventory carrying costs

MX150 dual-row, unshrouded headers are designed to mate with Molex MX150 connectors and are compatible with USCAR standard connectors. The unshrouded headers allow customers to standardize printed circuit board (PCB) designs by incorporating the shroud into an external shell, permitting rapid-design revisions while reducing work in process.

The unique breakaway design allows the customer to meet the increasing demands for design flexibility. These low-profile vertical headers are available in both single and dual-row configurations. A wide range of circuit sizes, plating options and pin lengths are available. The MX150 unshrouded breakaway headers are appropriate for both power and signal applications with current ratings up to 16 amperes per circuit.

These parts are the first in the series to be released. Additional parts in dual-row, as well as single-row versions will be available by June, 2006.

Features and Benefits

- High-temperature thermoplastic housing assures lead-free processing compatibility
- Unshrouded design offers flexibility in customer application
- Designed to be compatible with Molex MX150 connectors which accommodate wire-to-board applications
- Compatible with USCAR 1.50mm (.059") blade specifications in industry compatible format
- Unique breakaway design provides ability to break between rows and circuits
- 20-circuit master sticks provide distributor-friendly, value-added opportunities

SPECIFICATIONS

Reference Information

Packaging: Tubes
UL File No.: Pending
CSA File No.: Pending
Mates With: MX150 Connectors

Dual-Row (Series 33472)
Designed In: Millimeters

Electrical

Voltage: ≤ 500V DC Current: 16.0A

Contact Resistance: 20 milliohm max.
Dielectric Withstanding Voltage: 1500V
Insulation Resistance: 20 Megohms min.

Mechanical

Contact Retention to Housing: 0.7Kg min.
Mating Force: 6.5N (1.46 lbf) per contact max.
Unmating Force: 5N (1.12 lbf) per contact max.
Durability: Tin (Sn) — 25 cycles
Gold (Au) — 50 cycles

Physical

Housing: LCP

Contact: Copper (Cu) Alloy

Plating:

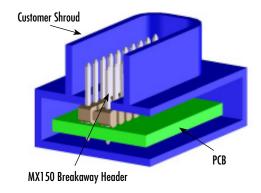
Contact Area — Tin (Sn) or Gold (Au) Solder Tail Area — Tin (Sn) Underplating — Nickel (Ni)

PCB Thickness: 1.57mm (0.062"), 2.36mm (.093")

or 3.18mm (.125") Orientation: Vertical

Operating Temperature: -40 to +125°C

Flammability: UL 94V-0



APPLICATIONS



molex® 3.50mm (.138") Pitch **MX150™ Dual-Row Unshrouded Breakaway Header**

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Outdoor applications

- Telecommunications devices
- Lighting
- Audio

Automotive related markets

- Automotive suppliers (tier 1 or tier 2)
- Trucking industry
- Specialty vehicle manufactures
- Automotive aftermarket and specialty equipment manufacturers

Recreational Markets

- Outdoor power equipment
- Recreational vehicles
- Snowmobiles
- Motorcycles
- ATV's

Indoor sealed applications

- Appliances
- Restaurant equipment makers
- Utility equipment manufacturers



ORDERING INFORMATION

Circuits	3.05mm (.120") PC Tail			4.75mm (.187") PC Tail		
	Overall Tin (Sn)	15µ" Select Gold (Au)	30μ″ Select Gold (Au)	Overall Tin (Sn)	15µ" Select Gold (Au)	30μ" Select Gold (Au)
2x10	75757-1401	75757-1201	75757-1301	75757-1402	75757-1202	75757-1302